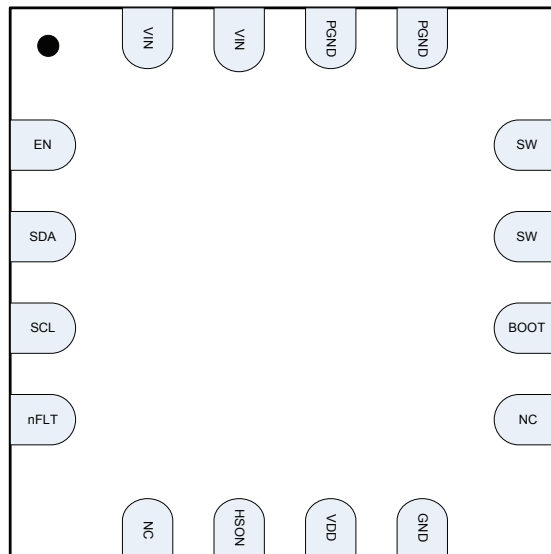


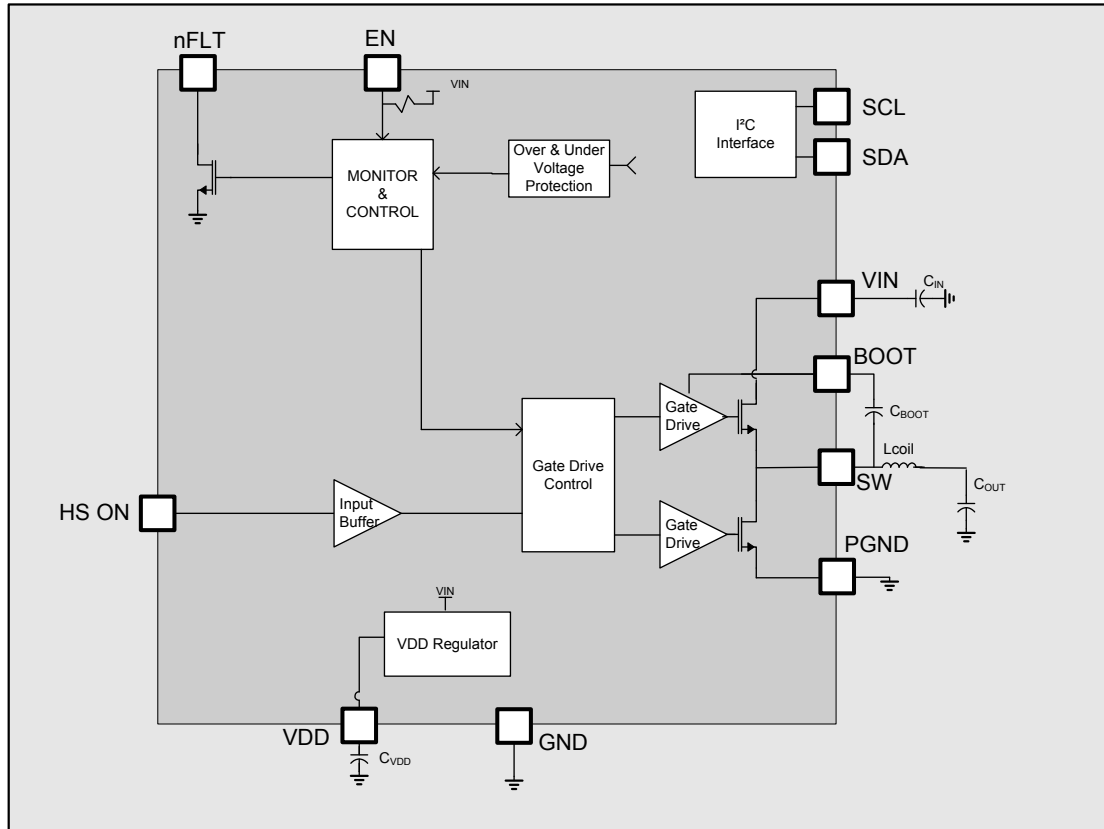
## Pin-out (Top view)



## Pin-out Configuration

Pin #	Pin Symbol	Function	Description
1	EN	Enable	Enable
2	SDA	I2C Serial Data	I2C Serial Data
3	SCL	I2C Serial Clock	I2C Serial Clock
4	nFLT	Status	Fault Status
5	NC	Reserved	Reserved
6	HSO	Driver	Driver high-side control
7	VDD	Supply	Device Supply
8	GND	GND	Device GND
9	NC	Reserved	Reserved
10	BOOT	Bootstrap Pin	Connected through 22nF capacitor to SW pin
11	SW	Switching Node	Connected to transmitter coil
12	SW	Switching Node	Connected to transmitter coil
13	PGND	Power GND	Power GND
14	PGND	Power GND	Power GND
15	VIN	Power Supply	Power Supply
16	VIN	Power Supply	Power Supply
17	PAD	Power PAD	Power GND

# Functional Block Diagram



## Absolute Maximum Ratings

Over operating free-air temperature range unless otherwise noted<sup>(1, 2)</sup>

Parameter	Value	Unit
VDD, EN, NFLT, SCL, SDA, HSON	-0.3 to 5.5	V
VIN	-0.3 to 20	V
BOOT	-0.3 to 25	V
SW	-1 to 20	V
Electrostatic Discharge – Human Body Model	+/-2k	V
Electrostatic Discharge – Charge Device Model	+/-500	V
Peak IR Reflow Temperature (10 to 30 seconds)	260	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.

## Thermal Characteristics

Symbol	Parameter	Value	Units
$\Theta_{JA}$	Thermal Resistance Junction to Air (Note 1)	33 - 36	°C/W
$\Theta_{JC}$	Thermal Resistance Junction to Case (Note 1)	1.2 - 3.9	°C/W
$T_{STG}$	Storage Temperature Range	-65 to 150	°C
$T_{J\ MAX}$	Maximum Junction Temperature	150	°C
$T_J$	Operating Junction Temperature Range	-40 to 125	°C

Note 1: Assumes 16LD 3x3 QFN with hi-K JEDEC board and 13.5 inch<sup>2</sup> of 1 oz Cu and 4 thermal vias connected to PAD

## Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VCC	Input Operating Voltage	4.2	12	16.5	V
LOUT	Transmitter Coil		6.0		μH
COUT	Output Filter Capacitor		100		nF
CIN	Input Bypass Capacitor		100		nF
CVDD	Internal Bypass Capacitor		100		nF
CBOOT	Bootstrap Capacitor		22		nF

## Electrical Characteristics (T=25°C unless otherwise specified)

Electrical Characteristics, T<sub>J</sub> = -40°C to 125°C (unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
<b>Output Stage</b>						
High Side Switch On Resistance	R <sub>DS(on)</sub>	ISW = -1A, T <sub>J</sub> =25°C			100	mΩ
Low Side Switch On Resistance		ISW = 1A, T <sub>J</sub> =25°C			100	mΩ
Max Output Current	I <sub>OUT</sub>			2.0		A
Over Current Detect	I <sub>OC</sub>	HS switch current	2.5			A
<b>VDD LDO Output</b>						
LDO Output Voltage	V <sub>LDO</sub>		4.75	5.0	5.25	V
LDO Output Current	I <sub>LDO</sub>				50	mA
Drop Out Voltage	LDODV	V <sub>in</sub> =5V, I <sub>out</sub> =50mA			400	mV

## Functional Description

Switching of the TS51231 transmitter driver is controlled by the wireless transmitter controller via the HSON pin. When the HSON pin is high, the high-side FET is switched on and the low-side FET is switched off. When the HSON pin is low, the high-side FET is switched off and the low-side FET is switched on.

# Application Schematic

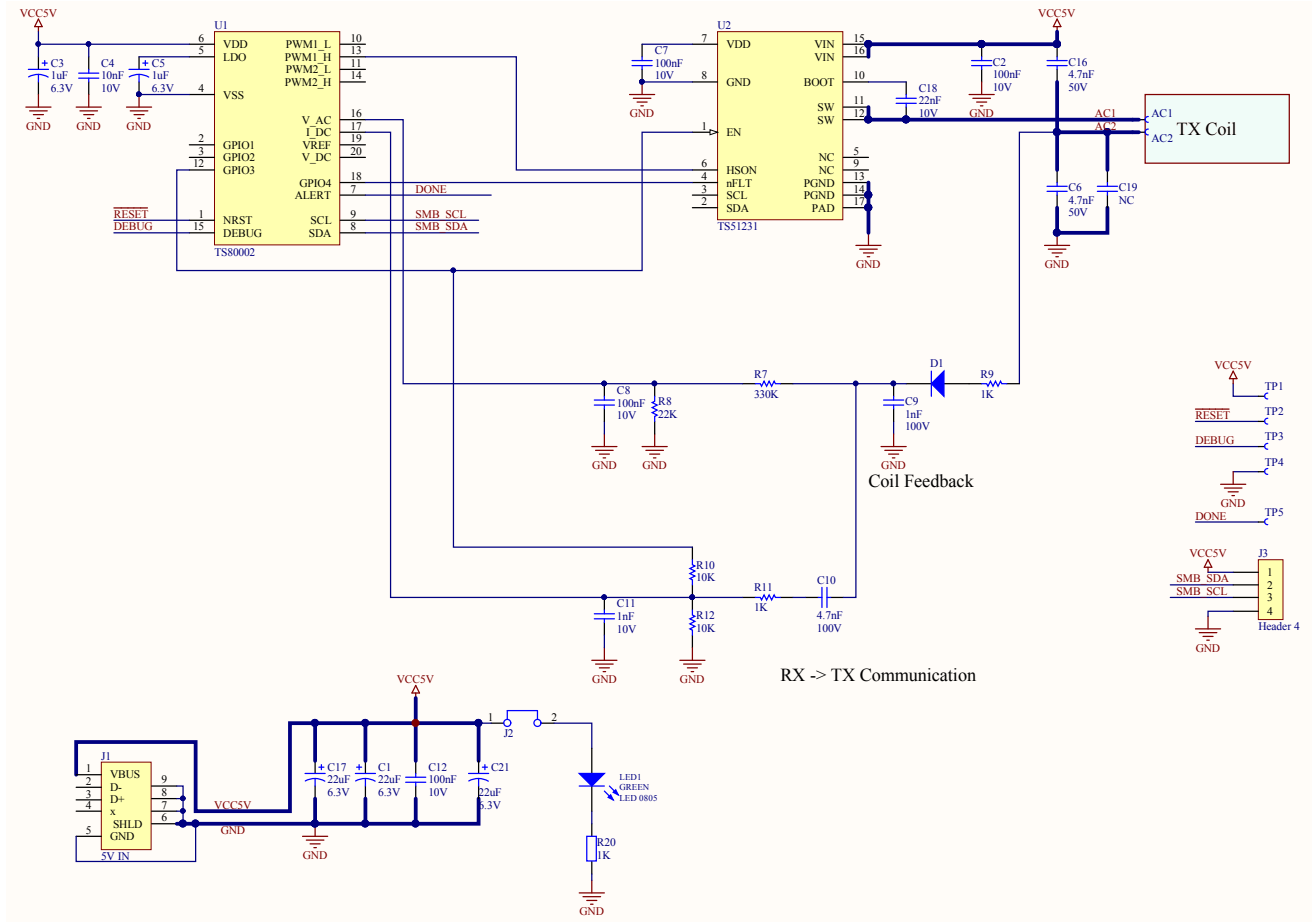
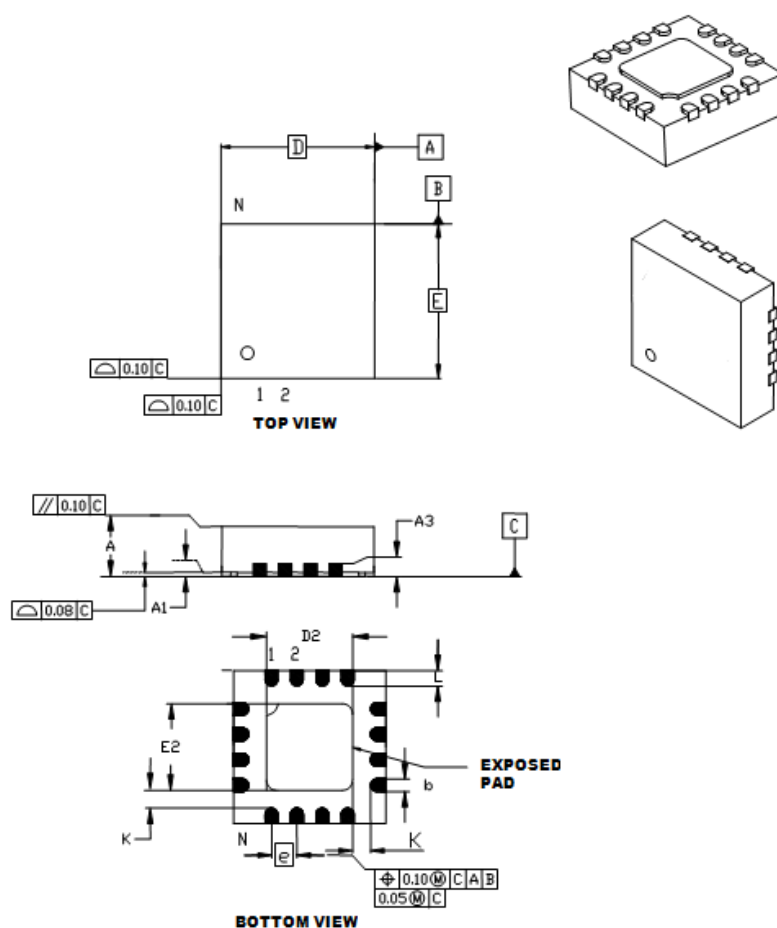


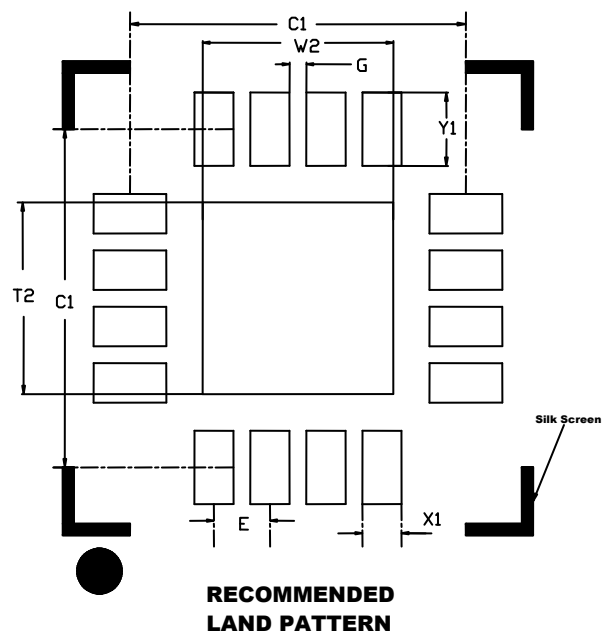
Figure 1: TS80002 Application Schematic

## Package Mechanical Drawings (all dimensions in mm)



Units		Millimeters		
Dimensions Limits		MIN	NOM	MAX
Number of Pins	N	16		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Length	D	3.00 BSC		
Exposed Pad Width	E2	1.55	1.70	1.80
Overall Width	E	3.00 BSC		
Exposed Pad Length	D2	1.55	1.70	1.80
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.30	0.40
Contact-to-Exposed Pad	K	0.20	-	-

# Recommended PCB Land Pattern



Units		Millimeters		
Dimensions Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	W2	-	-	1.70
Optional Center Pad Length	T2	-	-	1.70
Contact Pad Spacing	C1	-	3.00	-
Contact Pad Spacing	C2	-	3.00	-
Contact Pad Width (X16)	X1	-	-	0.35
Contact Pad Length (X16)	Y1	-	-	0.65
Distance Between Pads	G	0.15	-	-

Notes:  
Dimensions and tolerances per ASME Y14.5M.  
BSC: Basic Dimension. Theoretically exact values shown without tolerances.  
REF: Reference Dimension, usually without tolerance, for information only

---

## Ordering Information

Part Number	Description
TS51231-QFNR	Transmitter Driver

## RoHS and Reach Compliance

Semtech Corporation is fully committed to environmental quality. All Semtech Corporation materials and suppliers are fully compliant with RoHS (European Union Directive 2011/65/EU), REACH SVHC Chemical Restrictions (EC 1907/2006), IPC-1752 Level 3 materials declarations, and their subsequent amendments. Semtech Corporation maintains certified laboratory reports for all product materials, from all suppliers, which show full compliance to restrictions on the following:

- Cadmium (Cd)
- Chlorofluorocarbons (CFCs)
- Chlorinate Hydrocarbons (CHCs)
- Halons (Halogen free)
- Hexavalent Chromium (CrVI)
- Hydrobromofluorocarbons (HBFCs)
- Hydrochlorofluorocarbons (HCFCs)
- Lead (Pb)
- Mercury (Hg)
- Perfluorocarbons (PFCs)
- Polybrominated biphenyls (PBB)
- Polybrominated Diphenyl Ethers (PBDEs)





---

## Important Notice

Information relating to this product and the application or design described herein is believed to be reliable, however such information is provided as a guide only and Semtech assumes no liability for any errors in this document, or for the application or design described herein. Semtech reserves the right to make changes to the product or this document at any time without notice. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. Semtech warrants performance of its products to the specifications applicable at the time of sale, and all sales are made in accordance with Semtech's standard terms and conditions of sale.

SEMTECH PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS, OR IN NUCLEAR APPLICATIONS IN WHICH THE FAILURE COULD BE REASONABLY EXPECTED TO RESULT IN PERSONAL INJURY, LOSS OF LIFE OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. INCLUSION OF SEMTECH PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE UNDERTAKEN SOLELY AT THE CUSTOMER'S OWN RISK. Should a customer purchase or use Semtech products for any such unauthorized application, the customer shall indemnify and hold Semtech and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs damages and attorney fees which could arise.

The Semtech name and logo are registered trademarks of the Semtech Corporation. All other trademarks and trade names mentioned may be marks and names of Semtech or their respective companies. Semtech reserves the right to make changes to, or discontinue any products described in this document without further notice. Semtech makes no warranty, representation or guarantee, express or implied, regarding the suitability of its products for any particular purpose. All rights reserved.

© Semtech 2016

---

## Contact Information

Semtech Corporation  
1101 Resource Dr. Suite 121, Plano, Texas 75074  
Phone: (972) 231-1606

For general inquiries, sales and technical supports:  
[www.semtech.com/contact](http://www.semtech.com/contact)